



## Materials Declaration Form

<b>IPC</b>	1752	<b>Version</b>	2
<b>Form Type *</b>	Distribute		
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D

\*: Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	2018-02-08
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	Rossana Bonaccorso	<b>Representative Title</b>	ADG MD Champion
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement	
<b>Supplier Acceptance *</b>	true
<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
L9856-TR-LF	SOKU*U356BA6	A	3068	2018-02-08
	Amount	UoM	Unit type	ST ECOPACK Grade
	80	mg	Each	ECOPACK2

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NA	NiThPdAgAu	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
DSO	4.9-6-1.75	8	gull wing	
Comment	SO 08 STRIP SINGLE ISLAND 4+3+1			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : California Prop65 list, dated 15th December 2017			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.04	Leadframe	550

QueryList : REACH-15th January 2018				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	SOKU*U356BA6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	M-011 Other inorganic materials	3.713	mg	supplier	die	Silicon (Si)	7440-21-3		3.651	mg	983306	45650
				supplier	metallization	Aluminium (Al)	7429-90-5		0.006	mg	1616	75
				supplier	Passivation	Silicon Nitride	12033-89-5		0.023	mg	6193	286
				supplier	Passivation	Silicon Oxide	7631-86-9		0.033	mg	8885	411
Leadframe	M-004 Copper and its alloys	30.032	mg	supplier	alloy	Copper (Cu)	7440-50-8		29.709	mg	989245	371363
				supplier	alloy	Iron (Fe)	7439-89-6		0.030	mg	998	375
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.009	mg	300	113
				supplier	metallization	Nickel (Ni)	7440-02-0		0.044	mg	1465	550
				supplier	metallization	Palladium (Pd)	7440-05-3		0.002	mg	67	25
				supplier	metallization	Gold (Au)	7440-57-5		0.002	mg	67	25
				supplier	metallization	Silver (Ag)	7440-22-4		0.236	mg	7858	2950
Die attach	M-015 Other organic materials	1.031	mg	supplier	glue	Silver (Ag)	7440-22-4		0.938	mg	909796	11715
				supplier	glue	acrylate	Proprietary		0.052	mg	50436	650
				supplier	glue	Methacrylate	Proprietary		0.041	mg	39768	511
Bonding wires	M-011 Other inorganic materials	0.109	mg	supplier	wire	Gold (Au)	7440-57-5		0.108	mg	990826	1350
				supplier	wire	Copper (Cu)	7440-50-8		0.001	mg	9174	13
Encapsulation	M-011 Other inorganic materials	45.115	mg	supplier	mold compound	Silica, vitreous	60676-86-0		39.068	mg	865965	488350
				supplier	mold compound	Epoxy Resin	25068-38-6		3.384	mg	75008	42300
				supplier	mold compound	Phenol Resin	29690-82-2		2.256	mg	50006	28200
				supplier	mold compound	Carbon black	1333-86-4		0.226	mg	5009	2825
				supplier	mold compound	Bismuth (Bi)	7440-69-9		0.181	mg	4012	2263